Material Composition Declaration

EPC2090

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/15/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	4.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	3.8455	85.7069	89.2566	857069
	Silicon oxide	7631-86-9	0.0312	0.6961		6961
	Silicon nitride	12033-89-5	0.0087	0.1947		1947
	Gallium nitride	25617-97-4	0.0161	0.3581		3581
	Aluminum	7429-90-5	0.0479	1.0677		10677
	Aluminum nitride	24304-00-5	0.0025	0.0550		550
	Titanium	7440-32-6	0.0015	0.0329		329
	Titanium nitride	25583-20-4	0.0080	0.1778		1778
	Copper	7440-50-8	0.0008	0.0178		178
	Tungsten	7440-33-7	0.0051	0.1129		1129
	Polyimide		0.0375	0.8367		8367
Under Bump Metal	Titanium	7440-32-6	0.0003	0.0078	0.0853	78
	Copper	7440-50-8	0.0035	0.0775		775
Solder Bump	Copper	7440-50-8	0.3476	7.7482	10.6581	77482
	Nickel	7440-02-0	0.0207	0.4622		4622
	Tin	7440-31-5	0.1078	2.4037		24037
	Silver	7440-22-4	0.0020	0.0441		441
Sum in total:			4.4868	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.